

**Listing of Claims:**

1. (currently amended)      A pressure piece for effecting pressure contact within a power semiconductor module, the module includes a housing, at least one electrically insulating substrate having an insulating body with a plurality of metal connection tracks located therein and insulated from one another, at least one power semiconductor component located on and electrically connected to the connection tracks and at least partially resilient connection leads, for electrically connecting the connection tracks to a printed circuit board disposed outside the housing,

wherein the pressure piece is dimensionally stable and includes a plurality of pressure elements disposed on a first primary face of the pressure piece facing the printed circuit board, and the pressure elements space the primary face from the printed circuit board; and

wherein the pressure piece comprises a composite of an electrically insulating plastic and a metal core.

2. - 3. (canceled)

4. (presently amended)      The pressure piece of claim [[1]] 12, wherein the pressure piece comprises an electrically insulating, dimensionally stable, plastic.

5. - 7. (canceled)

8. (previously presented)      The pressure piece of claim 11, wherein the plurality of pressure elements includes at least two ribs which form a frame.

9. (previously presented) The pressure piece of claim 11, wherein the at least one rib has at least one notch to permit fluid to flow therethrough.

10. (previously presented) A pressure piece for effecting pressure contact within a power semiconductor module, the module includes a housing, at least one electrically insulating substrate having an insulating body with a plurality of metal connection tracks located therein and insulated from one another, at least one power semiconductor component located on and electrically connected to the connection tracks and at least partially resilient connection leads, for electrically connecting the connection tracks to a printed circuit board disposed outside the housing;

wherein the pressure piece is dimensionally stable and includes a plurality of pressure elements disposed on a first primary face of the pressure piece facing the printed circuit board, and the pressure elements space the primary face from the printed circuit board; and

wherein the pressure piece has at least one electrically insulated sheath for receiving a screw connection.

11. (previously presented) A pressure piece for effecting pressure contact within a power semiconductor module, the module includes a housing, at least one electrically insulating substrate having an insulating body with a plurality of metal connection tracks located therein and insulated from one another, at least one power semiconductor component located on and electrically connected to the connection tracks and at least partially resilient connection leads, for electrically connecting the connection tracks to a printed circuit board disposed outside the housing;

wherein the pressure piece is dimensionally stable and includes a plurality of pressure elements disposed on a first primary face of the pressure piece facing the printed circuit board, and the pressure elements space the primary face from the printed circuit board; and

wherein the plurality of pressure elements includes at least one rib.

12. (new) A pressure piece for effecting pressure contact within a power semiconductor module, the module includes a housing, at least one electrically insulating substrate having an insulating body with a plurality of metal connection tracks located therein and insulated from one another, at least one power semiconductor component located on and electrically connected to the connection tracks and at least partially resilient connection leads, for electrically connecting the connection tracks to a printed circuit board disposed outside the housing,

wherein the pressure piece is dimensionally stable and includes a plurality of pressure elements disposed on a first primary face of the pressure piece facing the printed circuit board, and the pressure elements space the primary face from the printed circuit board; and

wherein the plurality of pressure elements includes at least one prong.